

BB02-KD :- 2.54mm X 2.54mm (0.1" X 0.1") ELEVATED SOCKET, DUAL ROW, STRAIGHT, THROUGH HOLE, 4 TO 80 CONTACTS

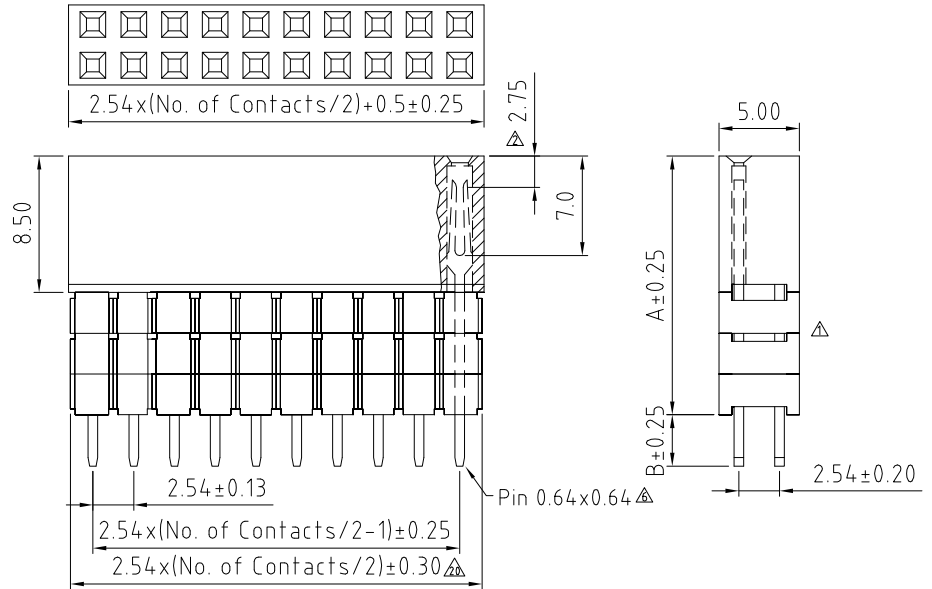
SPECIFICATIONS

CURRENT RATING 3 AMPS
 INSULATOR RESISTANCE 1000 MEGOHMS MIN.
 CONTACT RESISTANCE 20m OHMS MAX
 DIELECTRIC WITHSTANDING AC 600 V
 OPERATING TEMPERATURE -40°C TO +105°C
 CONTACT MATERIAL PHOSPHOR BRONZE
 INSULATOR MATERIAL THERMOPLASTIC, R UL 94V-0
 NYLON 6T : STANDARD
 PBT : SPECIAL OPTION
 PLATING GOLD OR TIN OVER 30-50U" NICKEL
 SOLDERABILITY: NYLON 6T - IR REFLOW: 260°C FOR 10 SEC
 WAVE: 230°C FOR 5-10 SEC
 MANUAL SOLDER: 350°C FOR 3-5 SEC
 PBT - MANUAL SOLDER: 330°C FOR 3-5 SEC
 (NOT SUITABLE FOR HI-TEMP PROCESS)

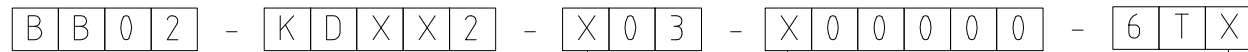
NOTES:

1. PACKED IN TRAY Δ
2. RECOMMENDED MATING PIN LENGTH = 6.0MM. Δ

MATES WITH: BB02-HE BB02-HQ BB02-TF
 BB02-HF BB02-HR BB02-TG
 BB02-HJ BB02-HU BB02-TH
 BB02-HP BB02-TD



HOW TO ORDER



NO. OF CONTACTS:
04 TO 80

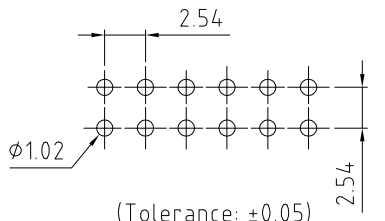
CONTACT PLATING OPTIONS:

- K = GOLD FLASH (STANDARD)
- A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- Δ T = BRIGHT TIN
- M = MATT TIN

- A: DIM. A=11.05, DIM. B=2.50
- B: DIM. A=11.05, DIM. B=7.35
- C: DIM. A=13.59, DIM. B=4.85
- D: DIM. A=16.13, DIM. B=2.30
- E: DIM. A=11.05, DIM. B=12.2
- F: DIM. A=13.59, DIM. B=9.65
- G: DIM. A=16.13, DIM. B=7.10
- Δ H: DIM. A=18.67, DIM. B=4.50
- I: DIM. A=18.67, DIM. B=3.0
- J: DIM. A=18.67, DIM. B=4.06
- Δ K: DIM. A=8.50, DIM. B=14.75
- Δ L: DIM. A=13.59, DIM. B=2.50
- Δ M: DIM. A=16.13, DIM. B=4.6

Δ WITH OR WITHOUT DECA-BDE
 BLANK = WITH (standard, RoHS compliant amount)
 N = WITHOUT (non-standard, zero amount)

INSULATOR MATERIAL: Δ
 6T = NYLON 6T (STANDARD)
 BLANK = PBT (Not suitable for new designs.)



RECOMMENDED PCB HOLE LAYOUT

REV.	DATE & DRN
10	15/03/04-A-MCI RELEASE
11	24/05/05-NYW
Δ	AMEND INSULATOR INSTALL
	ADD PLATING OPTION T.
	AMEND PACK METHOD.
12	22/11/05-NYW
Δ	AMEND PIN H-J OPTION
	AMEND PIN CONTACT POINT.
13	17/08/06 - NYW
Δ	ADD PLASTIC OPTION.
	DRAWING MODIFICATION.
14	28/05/07 - NYW
Δ	ADD PROFILE OPTION K.
	ADD NOTES 2.
15	18/07/08 - NYW
Δ	PLATING MODIFICATION.
16	22/02/08 - NYW
Δ	CHANGE PIN DIA 0.6 TO 0.64.
17	28/05/08 - NYW
Δ	ADD TIN PLATING
	ADD OPTION NYW
18	03/07/09 - NYW
Δ	DRAWING MODIFICATION.
19	18/05/09 - NYW
Δ	ADD DECA-BDE OPTION.
20	29/04/13 - NYW
Δ	ADD DIMENSION FORMULA.
21	13/05/13 - NYW
Δ	ADD PROFILE M OPTION.

Scale:	3:1	THIRD ANGLE	Unstated Tolerances:	Material
Drawn:	A.MCI		X. ± 0.30	SEE NOTE
App'd:	XXXX	Title	.X ± 0.25	NOT TO SCALE
Date:	13 MAY '13	SOCKET	.XX ± 0.15	Unit: mm
		Revision:	.XXX ± 0.10	
		2.1		

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Type:	BB02-KD
Drawing Number:	BB02-KD
Sheet	1 of 1
Drawing	© E and O E